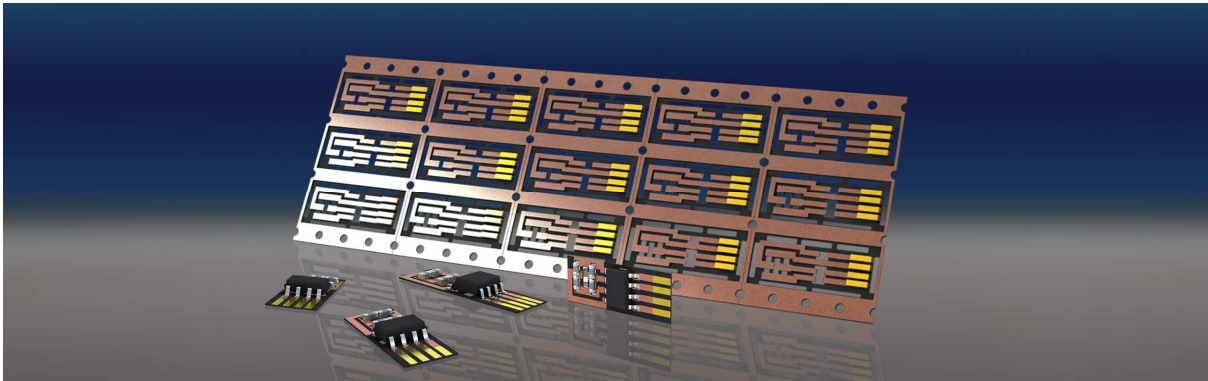


Flexible Substrates for Sensors



■ Epoxy

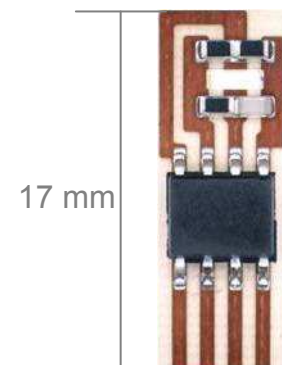
- Glass fibre filled epoxy tape
- Single side adhesive coating
- Thickness: 100 μm

■ Copper foil

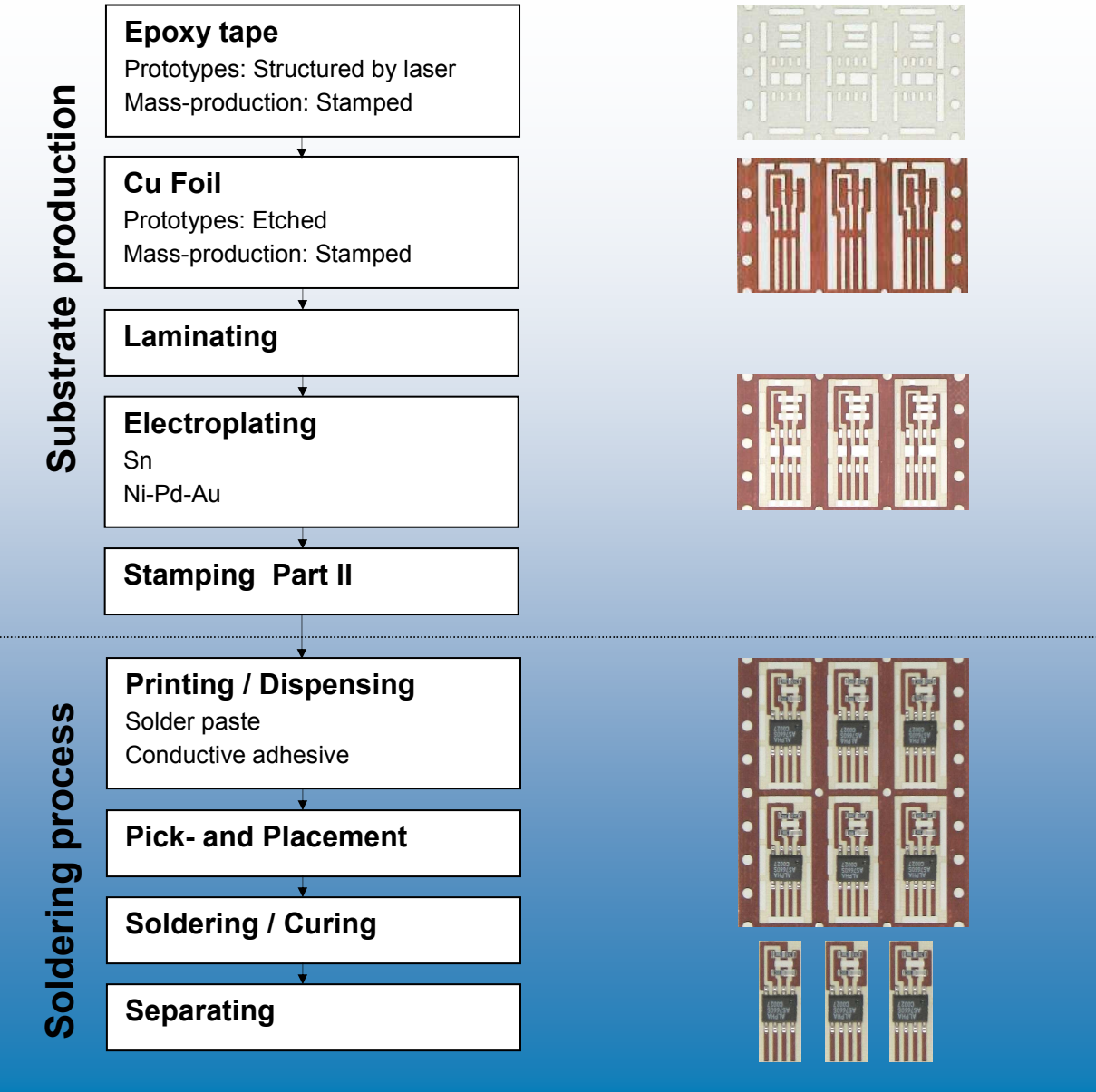
- Copper alloy: CuNi3
- Thickness: 150 μm

■ Laminate

- Qualified for Pb-free soldering
Test parameters:
Peak temperature: 250°C
Time above T_m (217°C) = 55 sec
- Temperature resistant according to IPC 2.4.13
Soldering bath: 30 sec at 260°C
- Various electroplated layer systems available for optimised wettability



Production Process – Reel to Reel



For further information please contact:

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